

Post-electric current treatment approaching high-performance flexible n-type Bi₂Te₃ thin films

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Figure S1 Calculated crystallinity of 0.5 A - Bi₂Te₃ f-TF.

Figure S2 (a) The SEM images of 0.6 A - Bi₂Te₃ thin film; (R-a) The repetitive SEM images of the 0.6 A - Bi₂Te₃ thin film.

Figure S3 The repetitive test of TE performance of the 0.5 A - Bi₂Te₃ thin film.

Figure S4 (a,b) The repetitive test result of the bending resistance of 0.5 A - Bi₂Te₃ thin film at bending radius of 9 mm and bending cycle of 800, respectively.

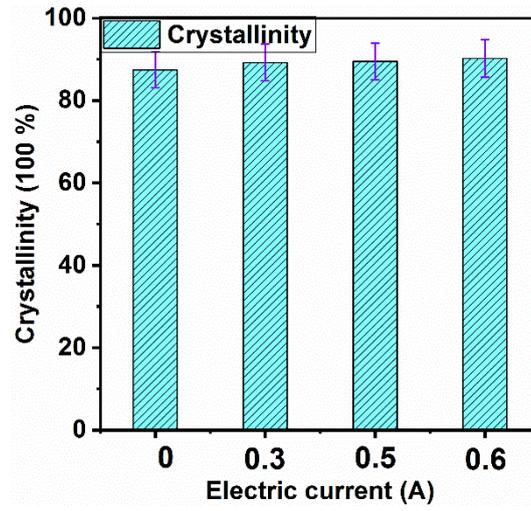


Figure S1. Calculated crystallinity of 0.5 A - Bi₂Te₃ f-TF.

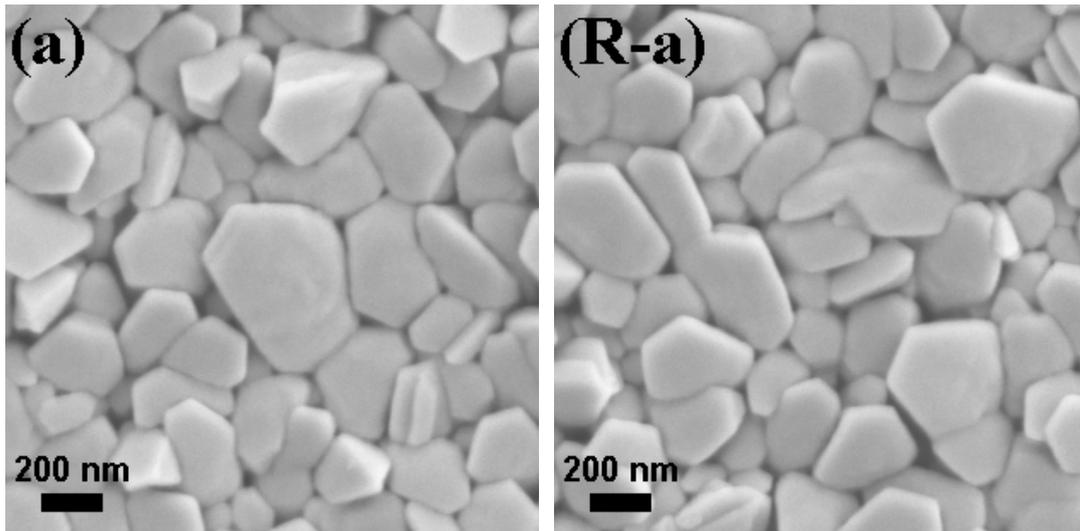


Figure S2. (a) The SEM images of 0.6 A - Bi₂Te₃ thin film. (R-a) The repetitive SEM images of the 0.6 A - Bi₂Te₃ thin film.

The repetitive SEM image was provided as shown in Figure R3. After 3 measure cycles and keep for a long time, the repetitive SEM images (**Figure S1b**) of the 0.6 A - Bi₂Te₃ thin film is basically the same with the **Figure S1a**.

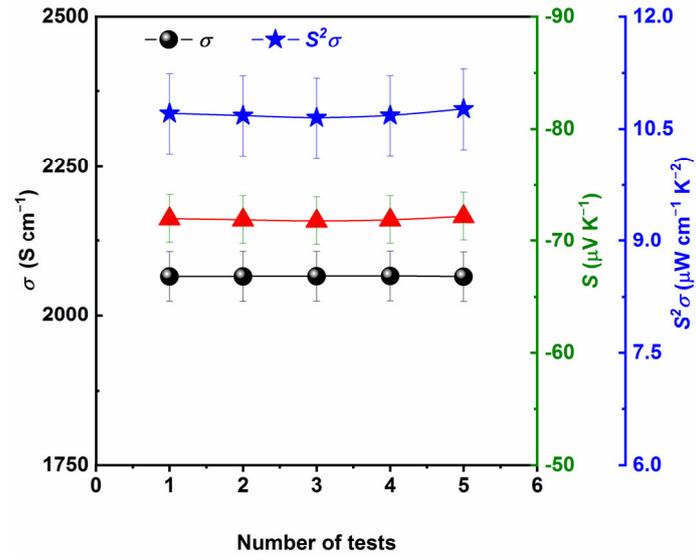


Figure S3. The repetitive test of TE performance of the 0.5 Å - Bi₂Te₃ thin film.

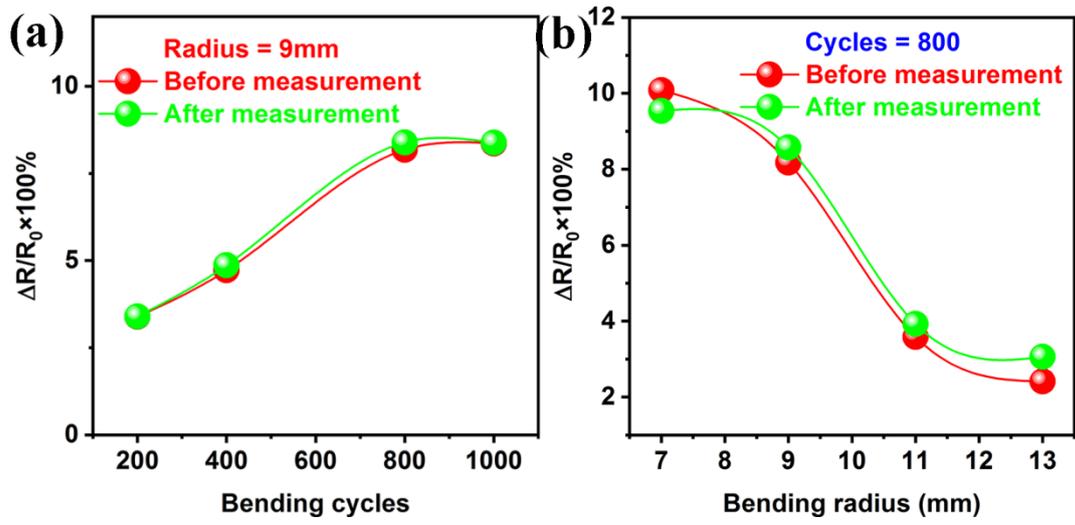


Figure S4. (a,b) The repetitive test result of the bending resistance of $0.5 \text{ \AA} - \text{Bi}_2\text{Te}_3$ thin film at bending radius of 9 mm and bending cycle of 800, respectively.

In this work, the n_e of the thin films ranges from 2.03×10^{20} to $3.84 \times 10^{20} \text{ cm}^{-3}$, which is higher than that of bulk Bi_2Te_3 ($1\sim 9 \times 10^{19} \text{ cm}^{-3}$) [1-3], which is responsible for the low Seebeck coefficient of the thin films.

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2. Hao, F.; Xing, T.; Qiu, P.; Hu, P.; Wei, T.; Ren, D.; Shi, X.; Chen, L.; Enhanced Thermoelectric Performance in n-Type Bi_2Te_3 -Based Alloys via Suppressing Intrinsic Excitation. *ACS Appl. Mater. Interfaces* 2018, 10, 21372–21380.
3. Shi, X. L.; Zou, J.; Chen, Z. G. Advanced Thermoelectric Design: From Materials and Structures to Devices. *Chem. Rev.* **2020**, 120, 7399-7515.